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RD Number: RD066

RD Title: TB67H400AFTG Evaluation Circuit BOM

Item No.	Designator	Quantity	Value	Part Number	Manufacturer	Description	Package	Not Mount
1	C_VCC	1	0.1µF 25V	_	_	Chip capacitor	3.2mm×1.6mm	
2	C_VM2	1	0.1µF 50V	—	—	Chip capacitor	3.2mm×1.6mm	
3	C_VRFA	1	0.1µF 25V	—	—	Chip capacitor	3.2mm×1.6mm	
4	C_VRFB	1	0.1µF 25V	—	—	Chip capacitor	3.2mm×1.6mm	
5	C_VM1	1	100µF 50V	—	—	Electrolytic capacitor		
6	C_VDD	1	10µF 25V	—	—	Electrolytic capacitor		
7	C_OSCM	0	Socket pin	—	—	Socket pin		√
8	C_OSCM	0	270pF 25V	—	—	Leaded capacitor	2.54mm pitch	√
9	C_OSCM	1	270pF 25V	—	_	Chip capacitor	3.2mm×1.6mm	
10	C_OAP	0	Not mount	—	—	Chip capacitor	3.2mm×1.6mm	√
11	C_OAM	0	Not mount	—	—	Chip capacitor	3.2mm×1.6mm	√
12	C_OBM	0	Not mount	—	—	Chip capacitor	3.2mm×1.6mm	√
13	C_OBP	0	Not mount	—	_	Chip capacitor	3.2mm×1.6mm	√
14	CON1	0	Connector	—	—	Connector 4P 2.5		√
15	CON2	1	Connector	—	—	Connector 2P 2.5		
16	CON3	1	Connector	—	—	Connector 2P 2.5		
17	CON4	0	Connector	—	—	Connector 3P 2.5		√
18	CON5	0	Connector	—	—	Connector 3P 2.5		√
19	OUT_A-	1	Check terminal	—	—	Check pin		
20	OUT_A+	1	Check terminal	—	_	Check pin		
21	OUT_B-	1	Check terminal	—	—	Check pin		
22	OUT_B+	1	Check terminal	_	—	Check pin		
23	RSA	1	Check terminal	_	_	Check pin		
24	RSB	1	Check terminal	_	—	Check pin		
25	VCC	1	Check terminal		_	Check pin		

26	VDD	1	Check terminal	-	_	Check pin		
27	VM	1	Check terminal	_	_	Check pin		
28	NC	0	Check terminal	_	_	Check pin		\checkmark
29	38	0	Check terminal	_	_	Check pin		\checkmark
30	39	0	Check terminal	_	-	Check pin		√
31	VREFB	1	Check terminal	_	—	Check pin		
32	42	1	Check terminal	_	—	Check pin		
33	OSCM	1	Check terminal	—	—	Check pin		
34	44	1	Check terminal	_	—	Check pin		
35	45	1	Check terminal	_	—	Check pin		
36	46	1	Check terminal	—	—	Check pin		
37	47	1	Check terminal	_	—	Check pin		
38	2	1	Check terminal	_	—	Check pin		
39	3	1	Check terminal	_	—	Check pin		
40	4	1	Check terminal	—	—	Check pin		
41	GND1	1	Check terminal	_	—	Check pin		
42	GND2	1	Check terminal	_	—	Check pin		
43	GND3	1	Check terminal	_	—	Check pin		
44	GND4	1	Check terminal	_	—	Check pin		
45	GND5	1	Check terminal	_	—	Check pin		
46	GND6	1	Check terminal	_	—	Check pin		
47	GND7	1	Check terminal	—	-	Check pin		
48	JP_VRF1	1	Pin header 2P	—	-	Jumper		
49	JP_VRF1	1	Jump socket	_	_	Short pin		
50	JP_VRF2	1	Pin header 2P	_	_	Jumper		
51	JP_VRF2	1	Jump socket	—	—	Short pin		
52	JP_VCC	1	Pin header 2P	—	-	Jumper		
53	JP_VCC	1	Jump socket	_	_	Short pin		
54	R_ID	0	100kΩ 0.25W	_	_	Leaded resistor	2.54mm pitch	\checkmark
55	R_MOUT	0	100kΩ 0.25W	_	—	Leaded resistor	2.54mm pitch	\checkmark
56	R_LOUT	0	100kΩ 0.25W	—	—	Leaded resistor	2.54mm pitch	\checkmark
57	R_OSCM	0	Socket pin	_	_	Socket pin		\checkmark

58	R_OSCM	0	5.1kΩ	_	_	Leaded resistor	2.54mm pitch	√
59	R_OSCM	1	5.1kΩ	_	_	Chip resistor	3.2mm×1.6mm	
60	R_VRF1	2	Socket pin	—	—	Socket pin		
61	R_VRF1	0	Not mount	—	—	Leaded resistor	2.54mm pitch	\checkmark
62	R_VRF2	2	Socket pin	_	_	Socket pin		
63	R_VRF2	0	Not mount	_	—	Leaded resistor	2.54mm pitch	\checkmark
64	R_RSA	1	0.22Ω 1W	_	—	Chip resistor	5.0mm×2.5mm	
65	R_RSB	1	0.22Ω 1W	—	—	Chip resistor	5.0mm×2.5mm	
66	SW2	1	Pin header 3P	_	—	Jumper		
67	SW2	1	Jump socket	—	—	Short pin		
68	SW3	1	Pin header 3P	—	—	Jumper		
69	SW3	1	Jump socket	—	—	Short pin		
70	SW4	1	Pin header 3P	—	—	Jumper		
71	SW4	1	Jump socket	_	—	Short pin		
72	SW39	0	Pin header 3P	—	—	Jumper		\checkmark
73	SW39	0	Jump socket	—	—	Short pin		\checkmark
74	SW42	1	Pin header 3P	_	—	Jumper		
75	SW42	1	Jump socket	—	—	Short pin		
76	SW44	1	Pin header 3P	—	—	Jumper		
77	SW44	1	Jump socket	—	—	Short pin		
78	SW45	1	Pin header 3P	—	—	Jumper		
79	SW45	1	Jump socket	—	—	Short pin		
80	SW46	1	Pin header 3P	—	—	Jumper		
81	SW46	1	Jump socket	—	—	Short pin		
82	SW47	1	Pin header 3P	—	—	Jumper		
83	SW47	1	Jump socket	—	—	Short pin		
84	IC1	1	TB67H400AFTG	TB67H400AFTG	TOSHIBA	Motor driver IC	QFN48	

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